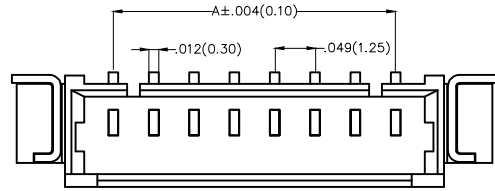
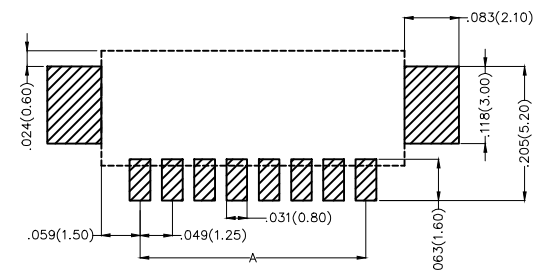
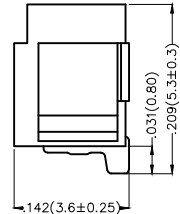
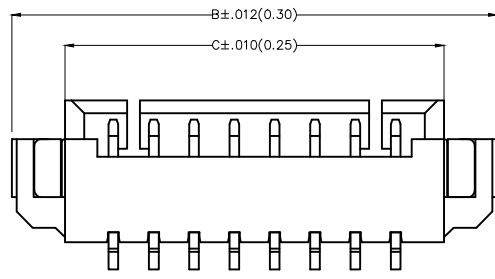


REV	LOCATIONS	DESCRIPTION	DATE	REVISED	APPD



Electrical
 Current Rating: 1.0A AC(rms)/DC
 Voltage Rating: 125V AC(rms)/DC
 Contact Resistance: 20 m Ω Max
 Insulation Resistance: 100 M Ω MIN
 Withstanding Voltage: 250V AC r.m.s
 Temperature Range—Operating: -40°C ~ +85°C
 Material and Plating
 Housing: PA9T(UL 94V-0)
 Contact Pin: Brass/ Tin plated
 Solder Tab: Copper alloy/ Tin plated



Recommended P.C.Board Layout

Ordering Information

FWF 125 04 — S XX B X 4 W5 M
 1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 125-Pitch 1.25mm	3 Distinction No. 04	4 Row Option S-Single Row	5 Circuits XX	6 Entry Angle B-90° Angle
7 Plating 2-Tin Plated	8 Material-Resin 4-PA9T	9 Color-Resin W5-Natural	10 Packaging M-Reel		

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF12504-SXXBX4W5M	ITEM NO. FWF12504	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X.±5° .X'±2° .XX'±1° .XXX'±0.5°	CHECKED BY JACOB	DATE 8/JUL/13	TITLE Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		REV 1
SCALE 5:1	SIZE A4		DRAWN BY CHERRY	DATE 8/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

A

B

B

C

C

D

D



E

E

F

F

Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C
2	FWF12504-S02B24W5M	.049(1.25)	.297(7.55)	.167(4.25)
3	FWF12504-S03B24W5M	.098(2.50)	.346(8.80)	.217(5.50)
4	FWF12504-S04B24W5M	.147(3.75)	.396(10.05)	.266(6.75)
5	FWF12504-S05B24W5M	.197(5.00)	.445(11.30)	.315(8.00)
6	FWF12504-S06B24W5M	.246(6.25)	.494(12.55)	.364(9.25)
7	FWF12504-S07B24W5M	.295(7.50)	.543(13.80)	.413(10.50)
8	FWF12504-S08B24W5M	.344(8.75)	.593(15.05)	.463(11.75)
9	FWF12504-S09B24W5M	.394(10.00)	.642(16.30)	.512(13.00)
10	FWF12504-S10B24W5M	.443(11.25)	.691(17.55)	.561(14.25)
11	FWF12504-S11B24W5M	.492(12.50)	.740(18.80)	.610(15.50)
12	FWF12504-S12B24W5M	.541(13.75)	.789(20.05)	.659(16.75)
13	FWF12504-S13B24W5M	.591(15.00)	.839(21.30)	.709(18.00)
14	FWF12504-S14B24W5M	.640(16.25)	.888(22.55)	.758(19.25)
15	FWF12504-S15B24W5M	.689(17.50)	.937(23.80)	.807(20.50)

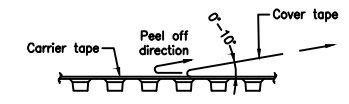
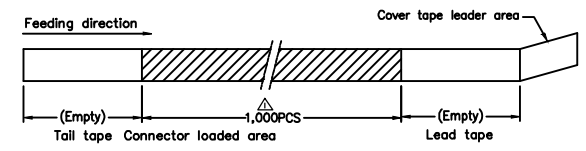
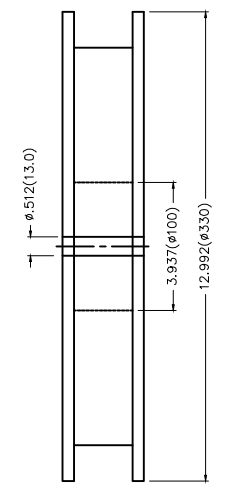
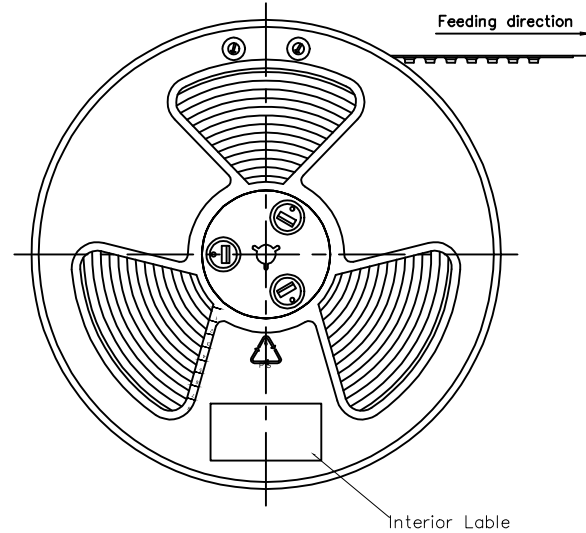
 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF12504-SXXBX4W5M	ITEM NO. FWF12504	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.±5°	CHECKED BY JACOB	DATE 8/JUL/13	TITLE Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		REV 1
SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX±1°	DRAWN BY CHERRY	DATE 8/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

1 2 3 4 5 6 7 8

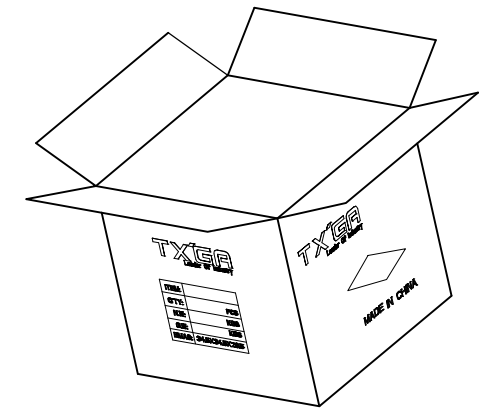
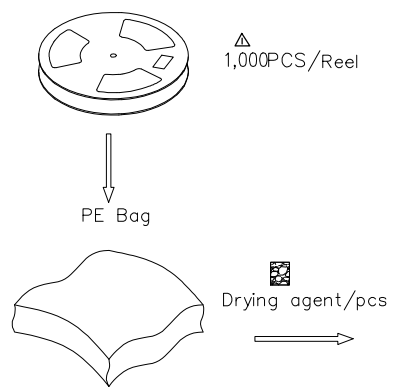
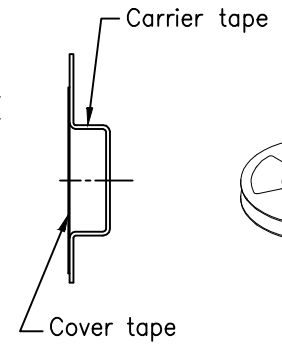
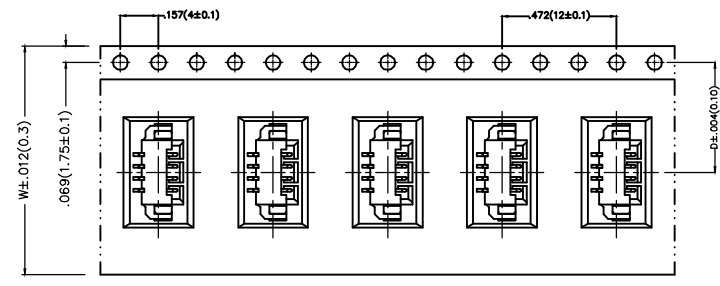
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	MPQ 1500PCS/Reel Change to 1000PCS/Reel	20150811	CHERRY	JACOB

Note:

- 10 sprocket hole cumulative tolerance ± 0.2
- Carrier camber is within 1.0mm in 100mm
- Material: White Conductive polystyrene Alloy 100% recyclable
- All dimensions meet EIA-481-3 requirements
- Component load per 13" reel: 1,000 pcs



Circuits (n)	Dimensions(in/mm)		Circuits (n)	Dimensions(in/mm)	
	D	W		D	W
2	.295(7.50)	.630(16.00)	10	.559(14.20)	1.260(32.00)
3	.295(7.50)	.630(16.00)	11	.559(14.20)	1.260(32.00)
4	.453(11.50)	.945(24.00)	12	.559(14.20)	1.260(32.00)
5	.453(11.50)	.945(24.00)	13	.795(20.20)	1.732(44.00)
6	.453(11.50)	.945(24.00)	14	.795(20.20)	1.732(44.00)
7	.559(14.20)	1.260(32.00)	15	.795(20.20)	1.732(44.00)
8	.559(14.20)	1.260(32.00)			
9	.559(14.20)	1.260(32.00)			



Feeding direction

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X. \pm 0.012(0.30)	X. \pm 5'	FRANK	8/JUL/13	FWF12504-SXXBX4W5M	FWF12504	
	X.X \pm 0.008(0.20)	.X \pm 2'	CHECKED BY	DATE	TITLE		
	X.XX \pm 0.006(0.15)	.XX \pm 1'	JACOB	8/JUL/13	Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		
SCALE	SIZE	X.XXX \pm 0.004(0.10)	.XXX \pm 0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
5:1	A4			CHERRY	8/JUL/13	REV 1	SHEET NO. 3/3